

- Member of the Texas Instruments *Widebus™* Family
- *EPIC™* (Enhanced-Performance Implanted CMOS) Submicron Process
- Typical V_{OLP} (Output Ground Bounce) $< 0.8\text{ V}$ at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$
- Typical V_{OHV} (Output V_{OH} Undershoot) $> 2\text{ V}$ at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$
- Latch-Up Performance Exceeds 250 mA Per JEDEC Standard JESD-17
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

description

This 16-bit bus transceiver and register is designed for low-voltage (3.3-V) V_{CC} operation.

The SN74LVC16646 can be used as two 8-bit transceivers or one 16-bit transceiver. The device consists of bus transceiver circuits, D-type flip-flops, and control circuitry arranged for multiplexed transmission of data directly from the input bus or from the internal registers.

Data on the A or B bus is clocked into the registers on the low-to-high transition of the appropriate clock (CLKAB or CLKBA) input. Figure 1 illustrates the four fundamental bus-management functions that can be performed with the SN74LVC16646.

Output-enable ($\overline{OE}$) and direction-control (DIR) inputs control the transceiver functions. In the transceiver mode, data present at the high-impedance port may be stored in either register or in both. The select-control (SAB and SBA) inputs can multiplex stored and real-time (transparent mode) data. The circuitry used for select control eliminates the typical decoding glitch that occurs in a multiplexer during the transition between stored and real-time data. DIR determines which bus receives data when $\overline{OE}$ is low. In the isolation mode ($\overline{OE}$ high), A data may be stored in one register and/or B data may be stored in the other register.

When an output function is disabled, the input function is still enabled and can be used to store and transmit data. Only one of the two buses, A or B, may be driven at a time.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry holds unused or floating data inputs at a valid logic level.

The SN74LVC16646 is characterized for operation from -40°C to 85°C .



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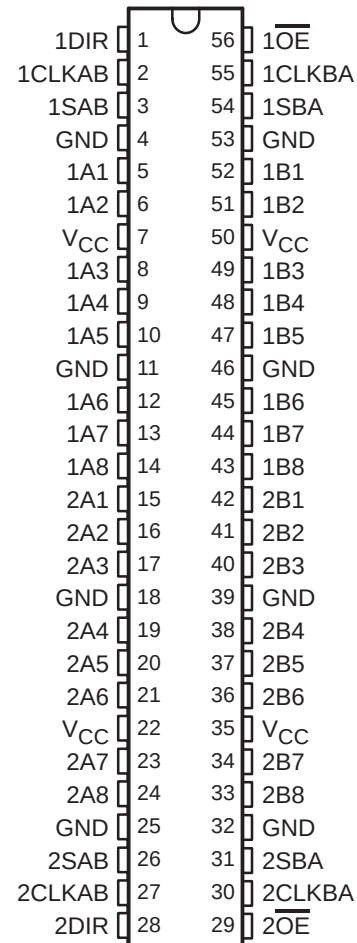
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DGG OR DL PACKAGE (TOP VIEW)



SN74LVC16646

16-BIT BUS TRANSCEIVER AND REGISTER

WITH 3-STATE OUTPUTS

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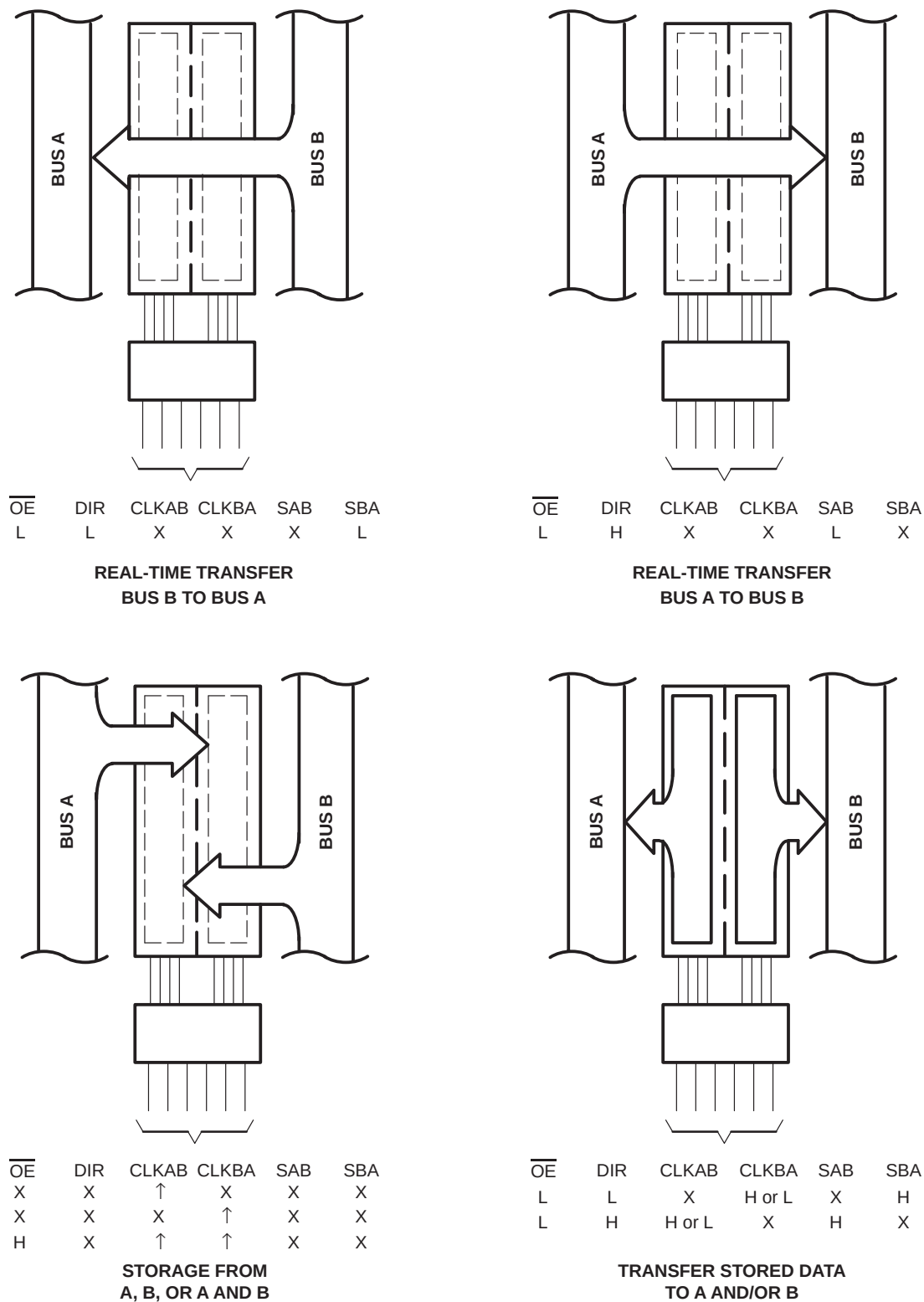
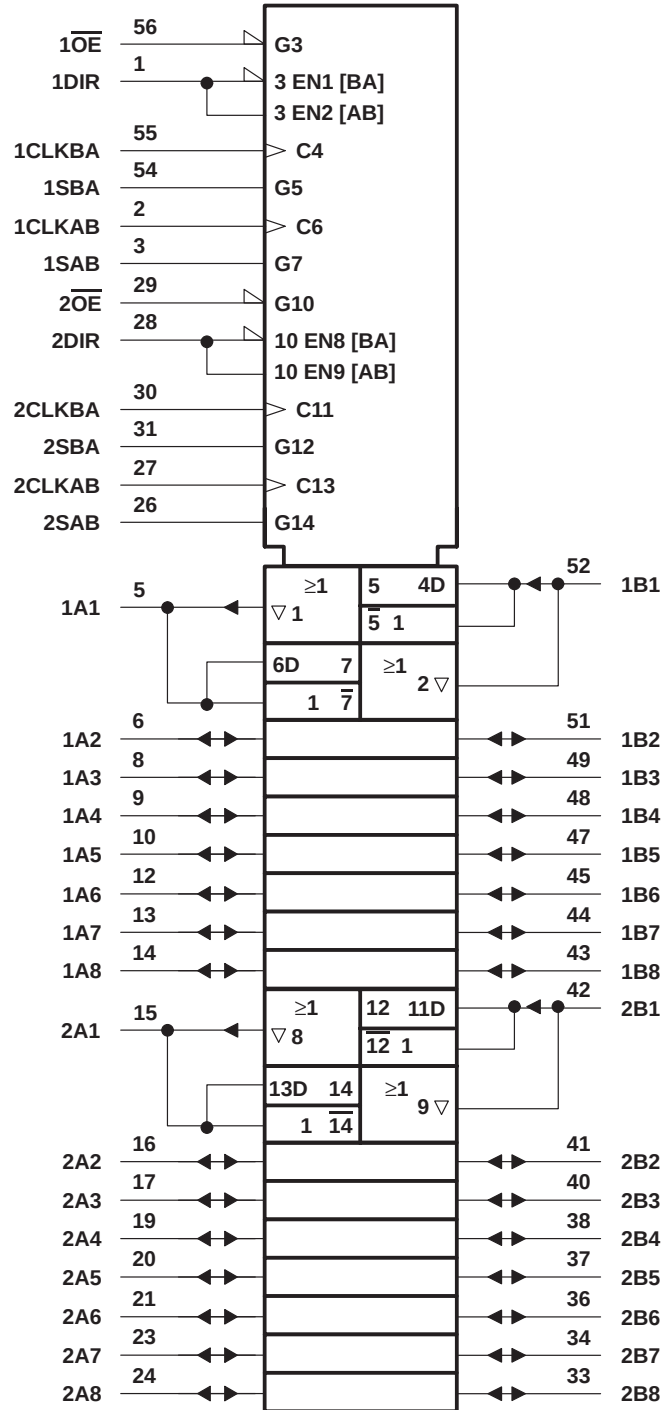


Figure 1. Bus-Management Functions

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16-BIT BUS TRANSCEIVER AND REGISTER
WITH 3-STATE OUTPUTS

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logic symbol†



† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

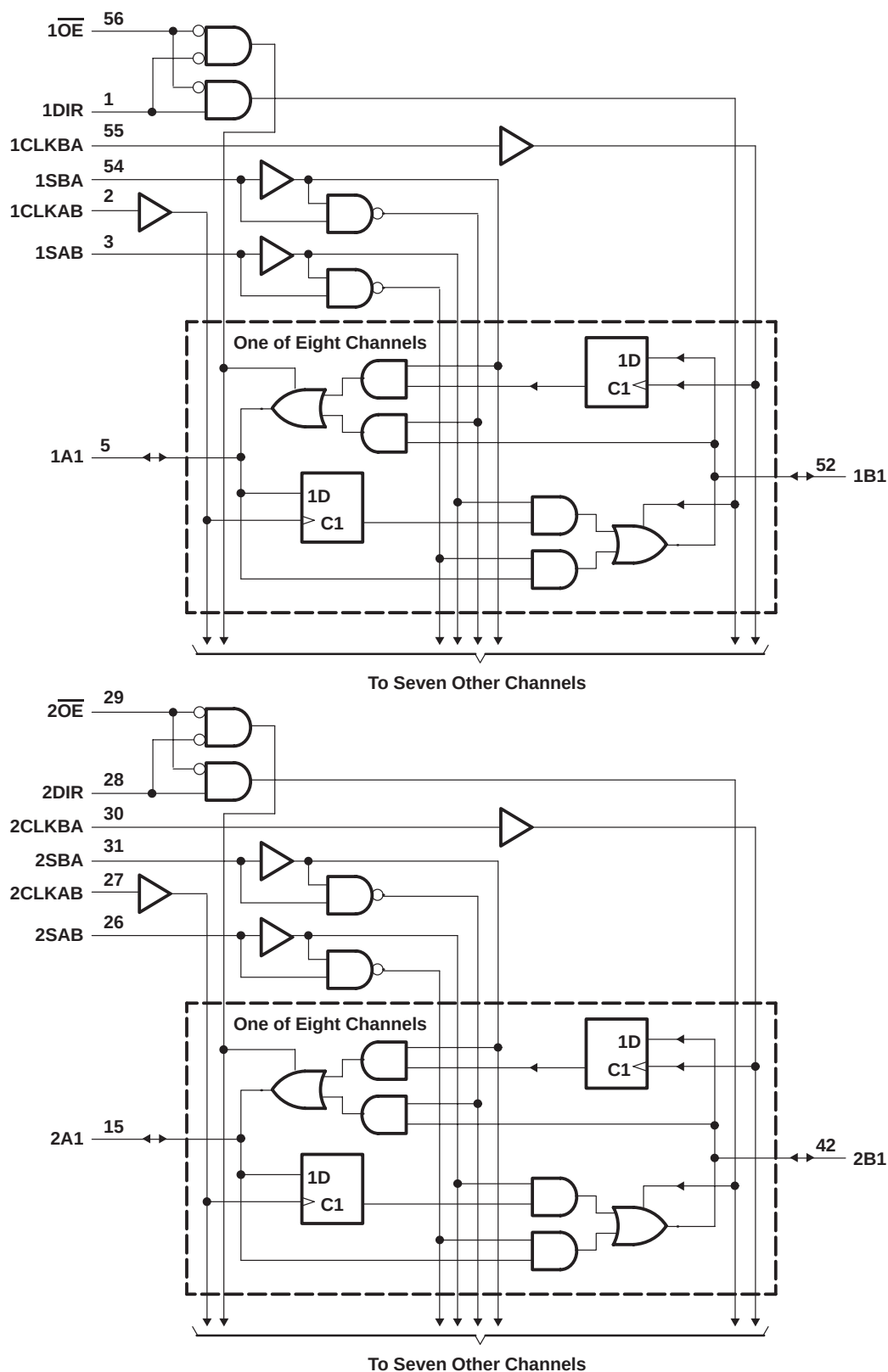
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logic diagram (positive logic)



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FUNCTION TABLE

INPUTS						DATA I/Os		OPERATION OR FUNCTION
OE	DIR	CLKAB	CLKBA	SAB	SBA	A1 THRU A8	B1 THRU B8	
X	X	↑	X	X	X	Input	Unspecified [†]	Store A, B unspecified [†]
X	X	X	↑	X	X	Unspecified [†]	Input	Store B, A unspecified [†]
H	X	↑	↑	X	X	Input	Input	Store A and B data
H	X	H or L	H or L	X	X	Input disabled	Input disabled	Isolation, hold storage
L	L	X	X	X	L	Output	Input	Real-time B data to A bus
L	L	X	H or L	X	H	Output	Input	Stored B data to A bus
L	H	X	X	L	X	Input	Output	Real-time A data to B bus
L	H	H or L	X	H	X	Input	Output	Stored A data to B bus

[†] The data output functions may be enabled or disabled by various signals at the OE and DIR inputs. Data input functions are always enabled; i.e., data at the bus terminals is stored on every low-to-high transition of the clock inputs.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[‡]

Supply voltage range, V_{CC}	–0.5 V to 4.6 V
Input voltage range, V_I : Except I/O ports (see Note 1)	–0.5 V to 4.6 V
I/O ports (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Output voltage range, V_O (see Notes 1 and 2)	–0.5 V to $V_{CC} + 0.5$ V
Input clamp current, I_{IK} ($V_I < 0$)	–50 mA
Output clamp current, I_{OK} ($V_O < 0$ or $V_O > V_{CC}$)	±50 mA
Continuous output current, I_O ($V_O = 0$ to V_{CC})	±50 mA
Continuous current through V_{CC} or GND	±100 mA
Maximum power dissipation at $T_A = 55^\circ\text{C}$ (in still air) (see Note 3): DGG package	1 W
DL package	1.4 W
Storage temperature range, T_{stg}	–65°C to 150°C

[‡] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. This value is limited to 4.6 V maximum.
 3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils. For more information, refer to the *Package Thermal Considerations* application note in the 1994 *ABT Advanced BiCMOS Technology Data Book*, literature number SCBD002B.



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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT
V _{CC}	Supply voltage		2.7	3.6	V
V _{IH}	High-level input voltage	V _{CC} = 2.7 V to 3.6 V	2		V
V _{IL}	Low-level input voltage	V _{CC} = 2.7 V to 3.6 V		0.8	V
V _I	Input voltage		0	V _{CC}	V
V _O	Output voltage		0	V _{CC}	V
I _{OH}	High-level output current	V _{CC} = 2.7 V		–12	mA
		V _{CC} = 3 V		–24	
I _{OL}	Low-level output current	V _{CC} = 2.7 V		12	mA
		V _{CC} = 3 V		24	
Δt/ΔV	Input transition rise or fall rate		0	10	ns/V
T _A	Operating free-air temperature		–40	85	°C

NOTE 4: Unused control inputs must be held high or low to prevent them from floating.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{CC} [†]	MIN	TYP [‡]	MAX	UNIT
V _{OH}		I _{OH} = –100 μA	MIN to MAX	V _{CC} –0.2			V
		I _{OH} = –12 mA	2.7	2.2			
			3	2.4			
		I _{OH} = –24 mA	3	2			
V _{OL}		I _{OL} = 100 μA	MIN to MAX			0.2	V
		I _{OL} = 12 mA	2.7			0.4	
		I _{OL} = 24 mA	3			0.55	
I _I	Control inputs	V _I = V _{CC} or GND	3.6			±5	μA
I _I (hold)	A or B ports	V _I = 0.8 V	3	75			μA
		V _I = 2 V		–75			
		V _I = 0 to 3.6 V	3.6			±500	
I _{OZ} [§]		V _O = V _{CC} or GND	3.6			±10	μA
I _{CC}		V _I = V _{CC} or GND, I _O = 0	3.6			40	μA
ΔI _{CC}		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	3 V to 3.6 V			500	μA
C _i	Control inputs	V _I = V _{CC} or GND	3.3	3			pF
C _{io}	A or B ports	V _O = V _{CC} or GND	3.3	7			pF

[†] For conditions shown as MIN or MAX, use the appropriate values under recommended operating conditions.

[‡] All typical values are at V_{CC} = 3.3 V, T_A = 25°C.

[§] For I/O ports, the parameter I_{OZ} includes the input leakage current.

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timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

			$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	100	0	80	MHz
t_w	Pulse duration, CLK high or low		4.5		4.5		ns
t_{su}	Setup time, A or B before CLKAB $\uparrow$ or CLKBA $\uparrow$	Data high or low	5		5		ns
t_h	Hold time, A or B after CLKAB $\uparrow$ or CLKBA $\uparrow$	Data high or low	0		0		ns

switching characteristics over recommended operating free-air temperature range, $C_L = 50\text{ pF}$ (unless otherwise noted) (see Figure 2)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		$V_{CC} = 2.7\text{ V}$		UNIT
			MIN	MAX	MIN	MAX	
f_{max}			100		80		MHz
t_{pd}	A or B	B or A	1.5	7		8	ns
	CLKAB or CLKBA	A or B	1.5	8.5		9.5	
	SAB or SBA		1.5	8.5		9.5	
t_{en}	$\overline{\text{OE}}$	A or B	1.5	8		9	ns
	DIR		1.5	8		9	
t_{dis}	$\overline{\text{OE}}$	A or B	1.5	8.5		9.5	ns
	DIR		1.5	8.5		9.5	

operating characteristics, $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$

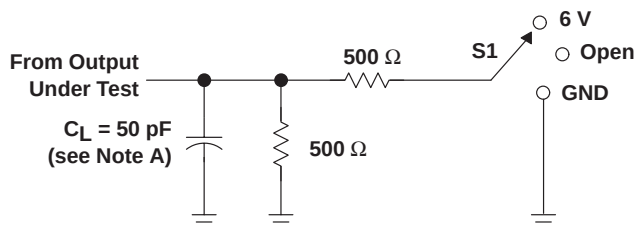
PARAMETER			TEST CONDITIONS	TYP	UNIT
C_{pd}	Power dissipation capacitance per transceiver	Outputs enabled	$C_L = 50\text{ pF}$, $f = 10\text{ MHz}$	17	pF
		Outputs disabled		4	

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16-BIT BUS TRANSCEIVER AND REGISTER WITH 3-STATE OUTPUTS

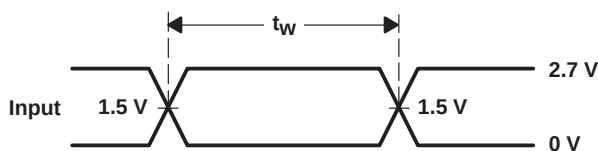
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PARAMETER MEASUREMENT INFORMATION

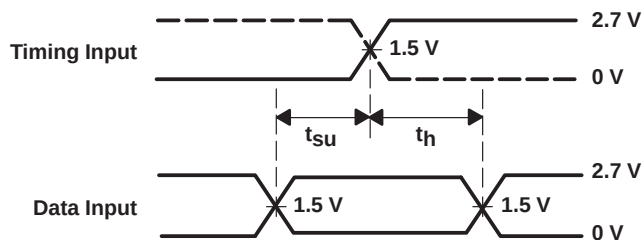


LOAD CIRCUIT FOR OUTPUTS

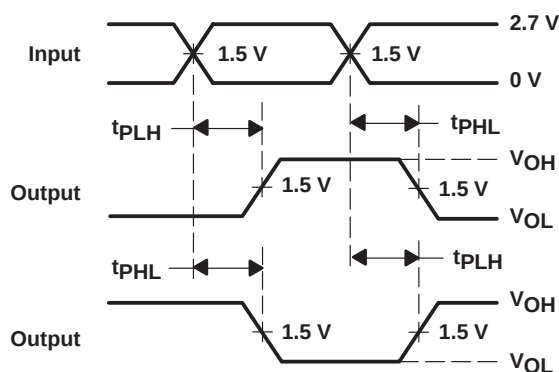
TEST	S1
t_{pd}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND



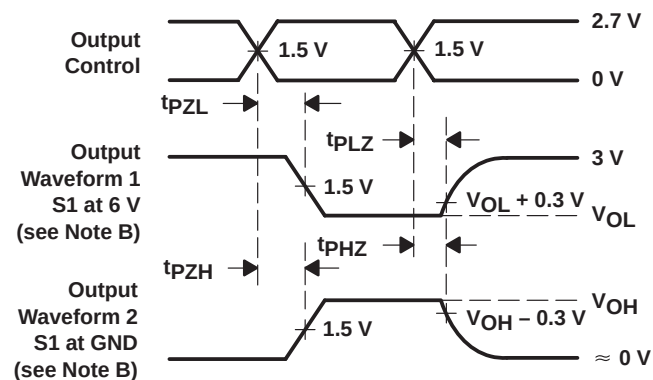
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50 \Omega$, $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - F. t_{PZL} and t_{PZH} are the same as t_{en} .
 - G. t_{PLH} and t_{PHL} are the same as t_{pd} .

Figure 2. Load Circuit and Voltage Waveforms

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